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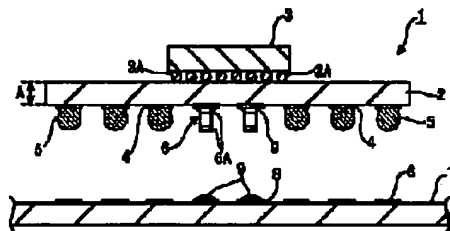
(54) **CONNECTION STRUCTURE OF BALL GRID
ARRAY TYPE PACKAGE**

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(57) Abstract:

PROBLEM TO BE SOLVED: To provide a connection structure which can reduce the distance between an integrated circuit chip and an electronic component, in the connection structure of a ball grid array type package.

SOLUTION: On a lower face side of a ball grid array type package 1, a solder ball 5 is provided, and the solder ball 5 is melted and resolidified through a reflow process, so as to connect it to another printed board 7. Furthermore, on the lower face side of the package 1, electronic components 8 are disposed, and a pair of terminal parts 8A provided at both end parts of the electronic component 6 are soldered to each of both printed boards 2, 7, so that both pads 4, 8 are connected to each other.



- 1...ボールグリッドアレイ型パッケージ
- 2...プリント基板
- 3...集積回路チップ
- 4...ハンダボール
- 5...電子部品
- 6 A...端子部
- 7...他のプリント基板